

Erfurt, 26th to 28th February 2023

35. ITG / GMM / GI - Workshop on Test Methods and Reliability of Circuits and

Systems		
Program Committee J. Alt Infineon Technologies AG H. Amrouch KIT B. Becker University of Freiburg A. Dalirsani Bosch	The Workshop on Test Methods and Reliability of Circuits and Systems is the most significant German forum to discuss trends, results and current problems in the area of test, diagnosis and reliability of digital, analog, mixed-signal and high-frequency-circuits. The exchange of ideas is an important intention of this workshop. The scope includes contributions discussing industrial practice as well as research. We strongly welcome practice-related technical reports and results as well as contributions presenting theoretical work from the following areas: Adaptive systems (e.g. self-repair, self-healing, self-awareness)	
R. Drechsler University of Bremen and DFKI S. Eggersglüß, Mentor, A Siemens Business P. Engelke Infineon Technologies AG G. Fey Hamburg Univ. of Technology AP. Fonseca Müller Bosch Sensortec GmbH M. Gössel University of Potsdam S. Hellebrand Paderborn University K. Hofmann Technical Univ. of Darmstadt S. Holst Kyushu Institute of Technology W. Hoppe	 Defect and failure modeling Diagnosis of failure causes Fault tolerance, resilience, robust and radiation-resistant systems Functional safety Hardware-oriented test and hardware-oriented safety Statistical and machine learning techniques for test and reliability System test and reliability Test and simulation of mixed-signal, RF and analog circuits Test generation, fault simulation, self-test and online-test Design-For-Test, DFT methodology Test costs and test quality Test standards such as IEEE 1149.x, IEEE 1687.x, IEEE P1838 	
Rheinmetall AG S. Huhn University of Bremen and DFKI R. Krenz-Baath Hamm-Lippstadt UAS M. Krstic Univ. of Potsdam and IHP GmbH V. Petrovic Brose L. Bolzani Poehls RWTH Aachen I. Polian University of Stuttgart	e workshop takes place in the Victor's Residenz-Hotel in Erfurt, ermany, and is organized by the University of Applied Sciences ordhausen and the University of Applied Sciences Hamm-Lippstadt. terested contributors should summarize their work onto no more than pages, which can be submitted via the workshop-website. The ntribution should describe the purpose, the novelty and practical uplications of the work. Accepted papers can be published in the formal workshop handout, if requested. For this purpose, the contribution could be extended to 4 ages.	
S. Sattler University Erlangen-Nürnberg M. Sauer Advantest Europe GmbH M. Schillinsky NXP Semiconductors Germany GmbH	Workshop-Homepage www.tuz-workshop.de Submission-Site https://easychair.org/conferences/?conf=tuz23	Important Dates Deadline for paper submission: 06. 20. Nov. 2022 Notification of acceptance: 18. Dec. 2022 Camera-ready-paper: 18. Jan. 2023
H. Schmidt IBM Germany GmbH M. Schölzel Nordhausen UAS J. Sepulveda Airbus Defence and Space M. Tahoori	General Chair Prof. Dr. Mario Schölzel Hochschule Nordhausen E-Mail: mschoelzel@hs-nordhausen.de	Program Chair Prof. Dr. Rene Krenz Hochschule Hamm-Lippstadt E-Mail: Rene.Krenz-Baath@hshl.de
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